

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (previously presented): A chip on film film carrier tape including a continuous insulating film, a wiring pattern formed of a conductor layer provided on a surface of the insulating film, and a row of sprocket holes provided on either lateral side of the wiring pattern on which electronic devices are to be mounted, characterized in that

a center section of the insulating layer other than opposite longitudinal edges where the sprocket holes are formed is provided with a support film formed on another surface of the insulating film, which surface is opposite to the surface on which the wiring pattern is provided.

2. (previously presented): A chip on film film carrier tape according to claim 1, wherein the row of sprocket holes are provided with a dummy wiring portion surrounding the holes.

3. (previously presented): A chip on film film carrier tape according to claim 2, wherein the dummy wiring portion is provided in the form of discrete islands each surrounding a sprocket hole.

4. (previously presented): A chip on film film carrier tape according to claim 3, wherein the tape has a predetermined distance between a longitudinal edge of the insulating layer and a longitudinal edge of the dummy wiring portion.

5. (previously presented): A chip on film film carrier tape according to claim 1, wherein the support film has a thickness which is equal to or less than that of the insulating layer.

6. (previously presented): A chip on film film carrier tape according to claim 2, wherein the support film has a thickness which is equal to or less than that of the insulating layer.

7. (previously presented): A chip on film film carrier tape according to claim 3, wherein the support film has a thickness which is equal to or less than that of the insulating layer.

8. (previously presented): A chip on film film carrier tape according to claim 4, wherein the support film has a thickness which is equal to or less than that of the insulating layer.

9. (previously presented): A chip on film film carrier tape according to claim 5, wherein the support film has a thickness of 25 to 50 μm .

10. (previously presented): A chip on film film carrier tape according to claim 6, wherein the support film has a thickness of 25 to 50 μm .

11. (previously presented): A chip on film film carrier tape according to claim 7, wherein the support film has a thickness of 25 to 50 μm .

12. (previously presented): A chip on film film carrier tape according to claim 8, wherein the support film has a thickness of 25 to 50 μm .

13. (withdrawn, currently amended): A method for producing a chip on film film carrier tape according to claim 1 including a continuous insulating film, a wiring pattern formed of a conductor layer provided on a surface of the insulating film, and a row of sprocket holes provided on either lateral side of the wiring pattern on which electronic devices are to be mounted, characterized in that
the method comprises

a step of attaching a support film to a center section of the insulating layer other than opposite longitudinal edges where the sprocket holes are to be formed, the support film being formed on another surface of the insulating film, which surface is opposite to the surface on which the wiring pattern is provided;

a step of forming the sprocket holes in the opposite longitudinal edges; and

a step of forming the wiring pattern as well as a dummy wiring portion surrounding the row of sprocket holes by forming a resist pattern on the conductor layer and etching the conductor layer.

14. (withdrawn): A method for producing a chip on film film carrier tape according to claim 13, wherein the dummy wiring portion is provided in the form of discrete islands each surrounding a sprocket hole.

15. (withdrawn): A method for producing a chip on film film carrier tape according to claim 13, wherein the method further comprises, after formation of the dummy wiring portion, a step of peeling off the support film.

16. (withdrawn): A method for producing a chip on film film carrier tape according to claim 14, wherein the method further comprises, after formation of the dummy wiring portion, a step of peeling off the support film.